

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IMC099T-T038	**Issued**	15. May 2021
MA#	MA003893726		
Package	PG-TSSOP-38-9	**Weight***	118.41 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.446	1.22	1.22	12214	12214
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	zinc	7440-66-6	0.060	0.05		506	
	non noble metal	iron	7439-89-6	1.199	1.01		10125	
	non noble metal	copper	7440-50-8	48.679	41.11	42.18	411114	421872
wires	noble metal	palladium	7440-05-3	0.003			25	
	non noble metal	copper	7440-50-8	0.293	0.25	0.25	2473	2498
encapsulation	organic material	carbon black	1333-86-4	0.191	0.16		1614	
	plastics	epoxy resin	-	7.453	6.29		62946	
	inorganic material	silicondioxide	60676-86-0	56.060	47.36	53.81	473443	538003
leadfinish	non noble metal	tin	7440-31-5	2.173	1.83	1.83	18348	18348
plating	noble metal	silver	7440-22-4	0.337	0.28	0.28	2848	2848
glue	plastics	epoxy resin	-	0.125	0.11		1054	
	noble metal	silver	7440-22-4	0.375	0.32	0.43	3163	4217
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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